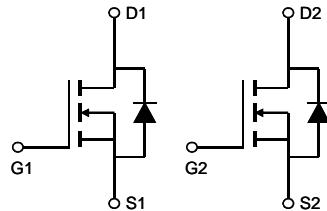


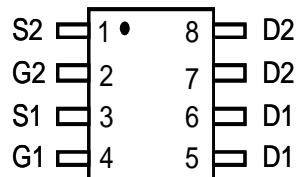
### General Description

The AO4832 uses advanced trench technology to provide excellent  $R_{DS(ON)}$  with low gate charge.  
This device is suitable for high side switch in SMPS and general purpose applications.



### Product Summary

$V_{DS}$	30V
$I_D$ (at $V_{GS}=10V$ )	10A
$R_{DS(ON)}$ (at $V_{GS}=10V$ )	< 13mΩ
$R_{DS(ON)}$ (at $V_{GS}=4.5V$ )	< 17.5mΩ



### Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$I_D$	10	A
Current		8	
Pulsed Drain Current <sup>C</sup>	$I_{DM}$	55	
Avalanche Current <sup>C</sup>	$I_{AS}, I_{AR}$	22	A
Avalanche energy L=0.1mH <sup>C</sup>	$E_{AS}, E_{AR}$	24	mJ
Power Dissipation <sup>B</sup>	$P_D$	2	W
		1.3	
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	°C

### Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient <sup>A</sup> $t \leq 10s$	$R_{\theta JA}$	48	62.5	°C/W
Maximum Junction-to-Ambient <sup>A,D</sup> Steady-State		74	90	°C/W
Maximum Junction-to-Lead	$R_{\theta JL}$	32	40	°C/W

Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>STATIC PARAMETERS</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	30			V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{DS}=30\text{V}, V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			1 5	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm20\text{V}$			100	nA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.5	1.9	2.5	V
$I_{\text{D(ON)}}$	On state drain current	$V_{GS}=10\text{V}, V_{DS}=5\text{V}$	55			A
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}, I_D=10\text{A}$		10.8	13	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}, I_D=8\text{A}$		14	17.5	$\text{m}\Omega$
$g_{\text{FS}}$	Forward Transconductance	$V_{DS}=5\text{V}, I_D=10\text{A}$		43		S
$V_{\text{SD}}$	Diode Forward Voltage	$I_S=1\text{A}, V_{GS}=0\text{V}$		0.75	1	V
$I_S$	Maximum Body-Diode Continuous Current				2.5	A
<b>DYNAMIC PARAMETERS</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=15\text{V}, f=1\text{MHz}$	610	760	910	pF
$C_{\text{oss}}$	Output Capacitance		88	125	160	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		40	70	100	pF
$R_g$	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$	0.8	1.6	2.4	$\Omega$
<b>SWITCHING PARAMETERS</b>						
$Q_g(10\text{V})$	Total Gate Charge	$V_{GS}=10\text{V}, V_{DS}=15\text{V}, I_D=10\text{A}$	11	14	17	nC
$Q_g(4.5\text{V})$	Total Gate Charge		5	6.6	8	nC
$Q_{\text{gs}}$	Gate Source Charge			2.4		nC
$Q_{\text{gd}}$	Gate Drain Charge			3		nC
$t_{\text{D(on)}}$	Turn-On Delay Time	$V_{GS}=10\text{V}, V_{DS}=15\text{V}, R_L=1.5\Omega, R_{\text{GEN}}=3\Omega$		4.4		ns
$t_r$	Turn-On Rise Time			9		ns
$t_{\text{D(off)}}$	Turn-Off Delay Time			17		ns
$t_f$	Turn-Off Fall Time			6		ns
$t_{\text{rr}}$	Body Diode Reverse Recovery Time	$I_F=10\text{A}, dI/dt=500\text{A}/\mu\text{s}$	5.6	7	8	ns
$Q_{\text{rr}}$	Body Diode Reverse Recovery Charge	$I_F=10\text{A}, dI/dt=500\text{A}/\mu\text{s}$	6.4	8	9.6	nC

A. The value of  $R_{\theta JA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ\text{C}$ . The value in any given application depends on the user's specific board design.

B. The power dissipation  $P_D$  is based on  $T_{J(\text{MAX})}=150^\circ\text{C}$ , using  $\leq 10\text{s}$  junction-to-ambient thermal resistance.

C. Repetitive rating, pulse width limited by junction temperature  $T_{J(\text{MAX})}=150^\circ\text{C}$ . Ratings are based on low frequency and duty cycles to keep initial  $T_J=25^\circ\text{C}$ .

D. The  $R_{\theta JA}$  is the sum of the thermal impedance from junction to lead  $R_{\theta JL}$  and lead to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300μs pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-ambient thermal impedance which is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, assuming a maximum junction temperature of  $T_{J(\text{MAX})}=150^\circ\text{C}$ . The SOA curve provides a single pulse rating.

## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

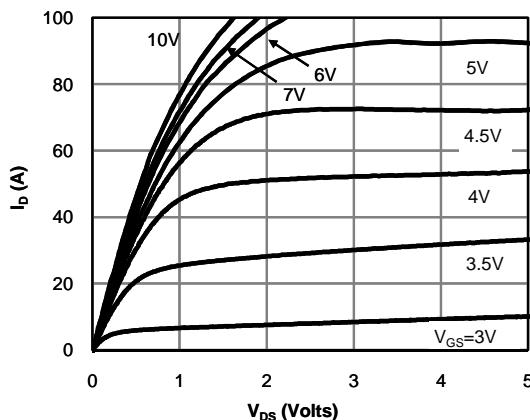


Fig 1: On-Region Characteristics (Note E)

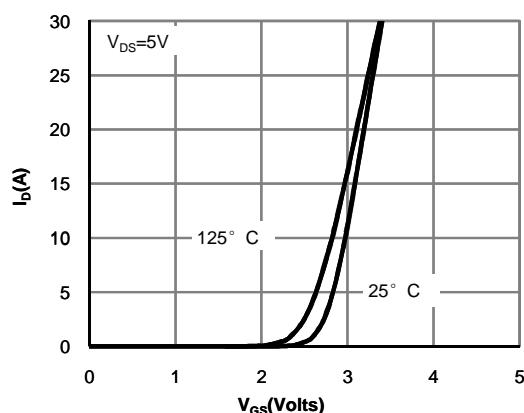


Figure 2: Transfer Characteristics (Note E)

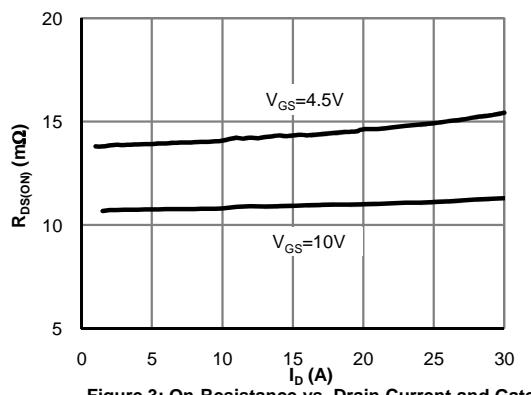


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

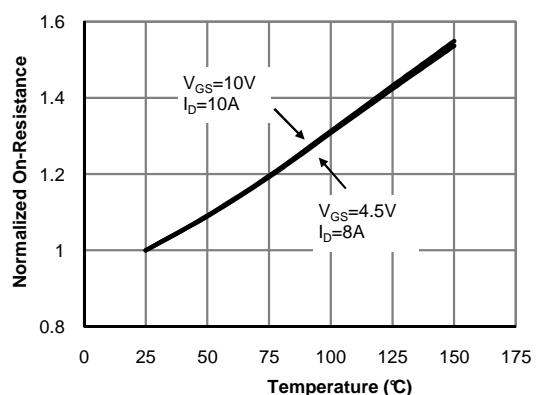


Figure 4: On-Resistance vs. Junction Temperature (Note E)

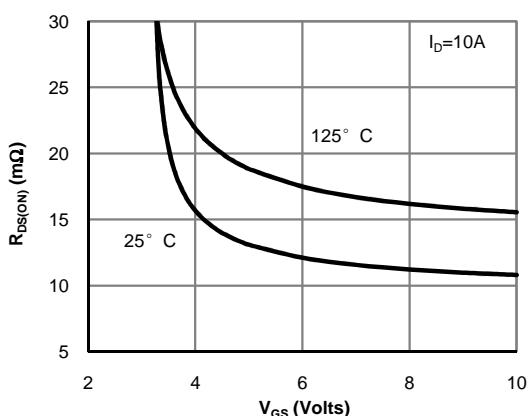


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

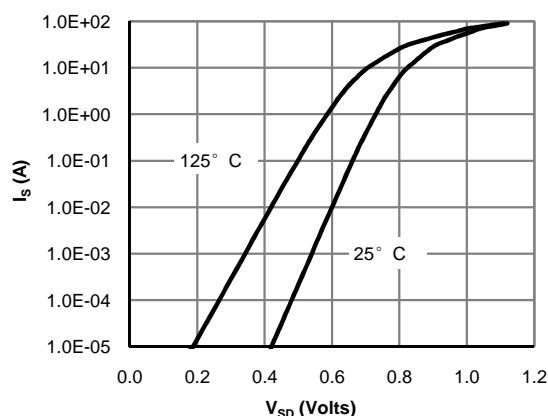


Figure 6: Body-Diode Characteristics (Note E)

## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

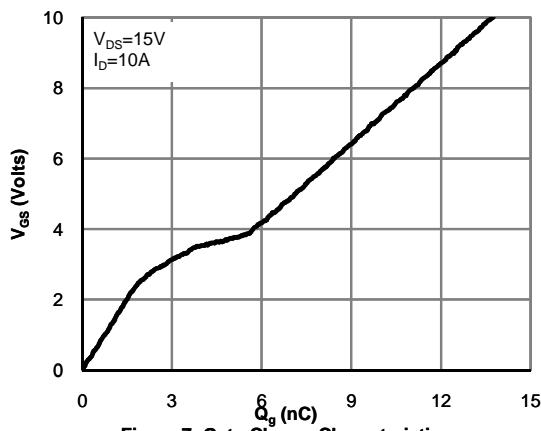


Figure 7: Gate-Charge Characteristics

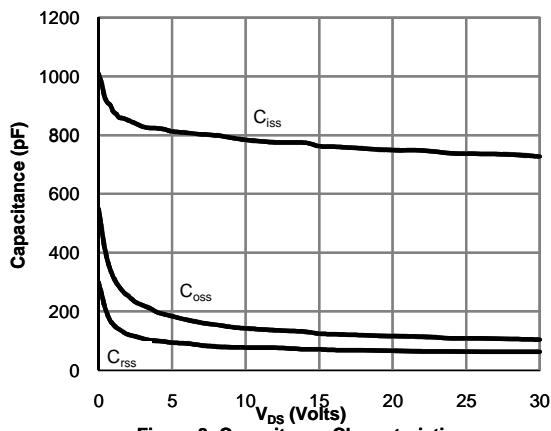


Figure 8: Capacitance Characteristics

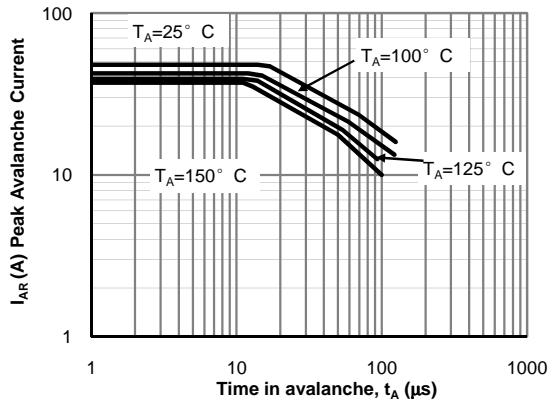


Figure 9: Single Pulse Avalanche capability (Note C)

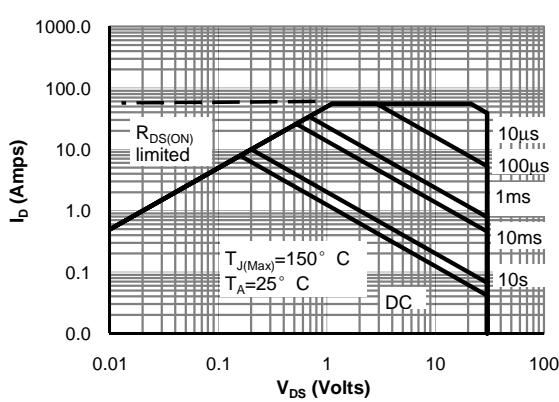


Figure 10: Maximum Forward Biased Safe Operating Area (Note F)

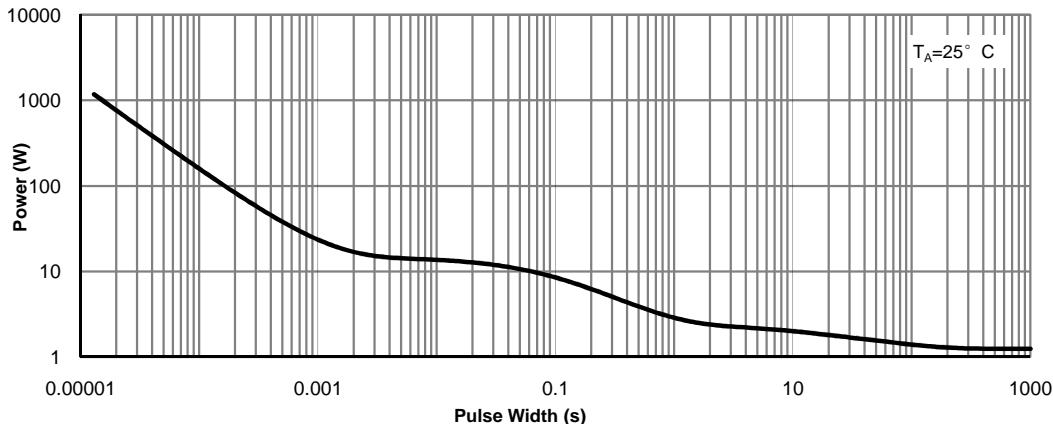


Figure 11: Single Pulse Power Rating Junction-to-Ambient (Note F)

## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

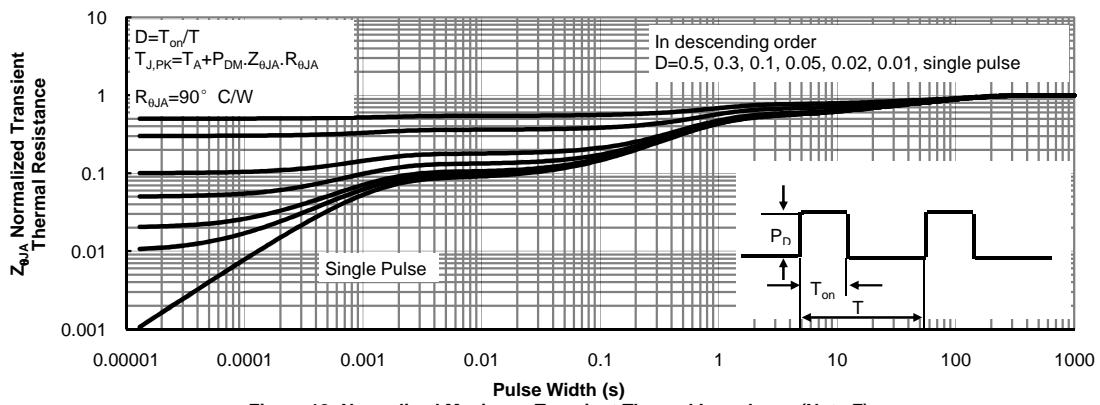
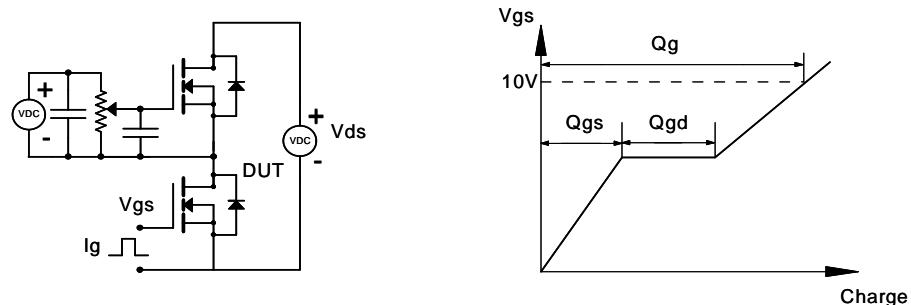
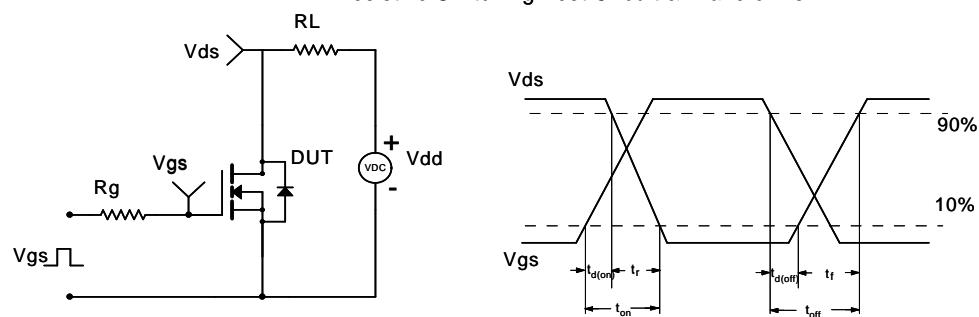


Figure 12: Normalized Maximum Transient Thermal Impedance (Note F)

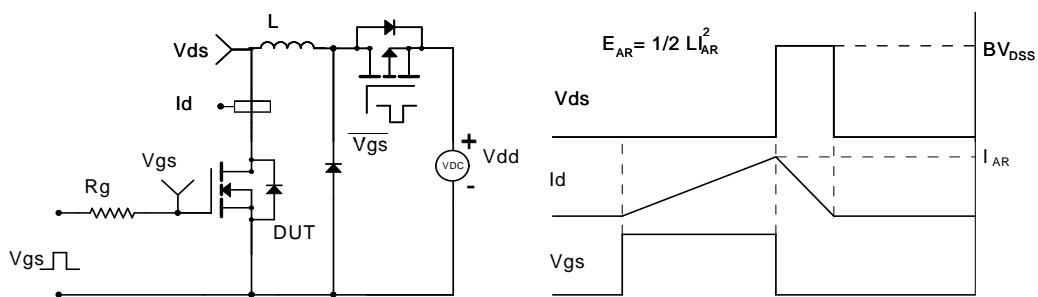
Gate Charge Test Circuit & Waveform



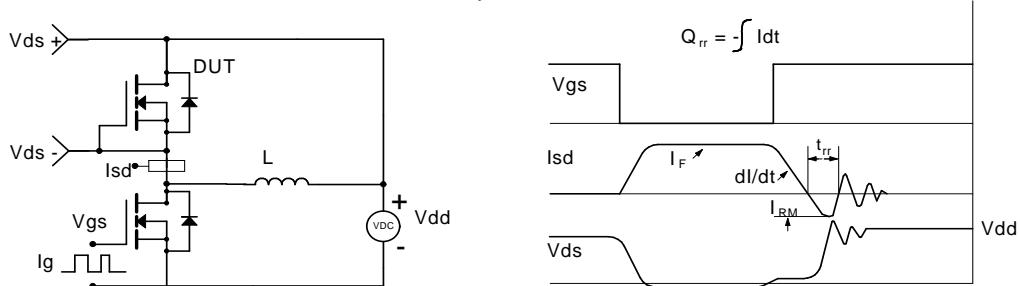
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

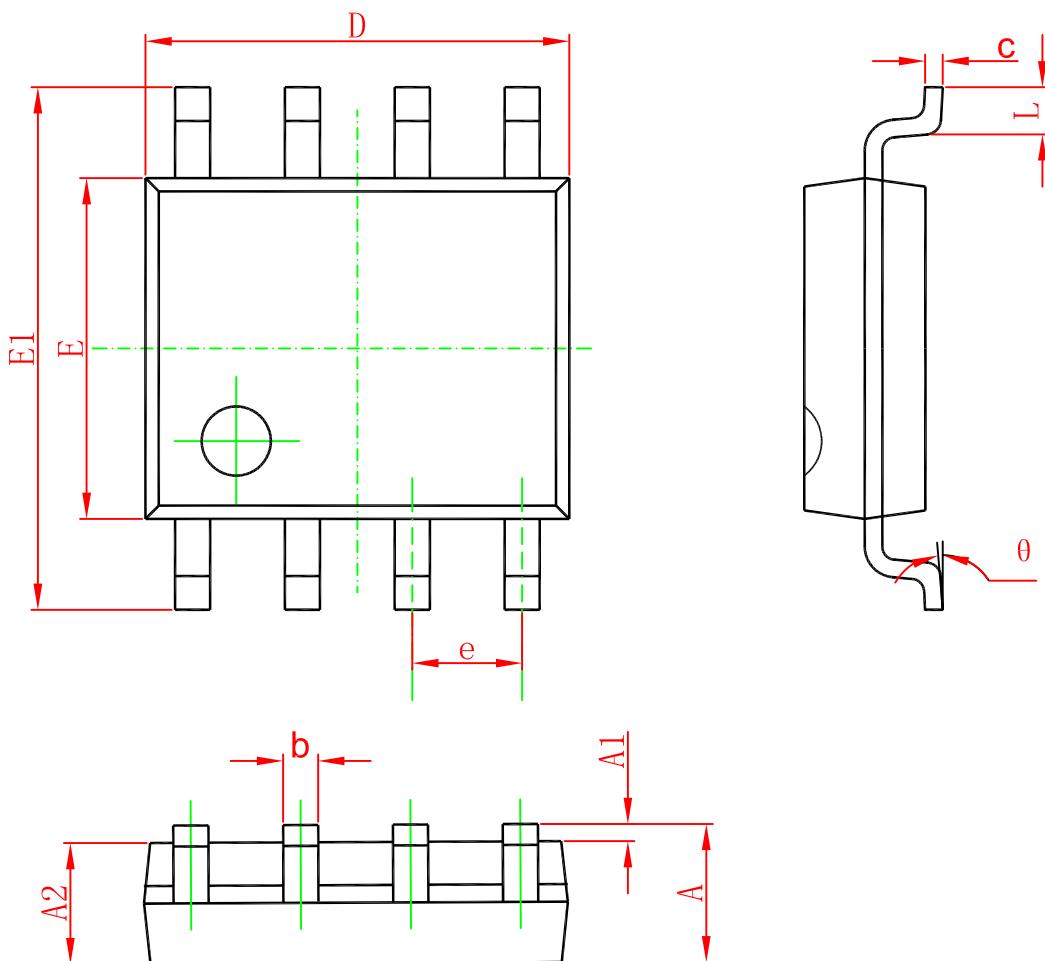


Diode Recovery Test Circuit & Waveforms



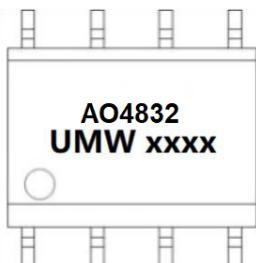
## PACKAGE OUTLINE DIMENSIONS

SOP-8



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

## Marking



## Ordering information

Order code	Package	Baseqty	Deliverymode
UMW AO4832	SOP-8	3000	Tape and reel

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